

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	ANALOG MEMS SENSORS/26/16483	
1.3 Title of PCI	Change of Main Die Identification on Product Box PQ Label for Previous NXP Sensor Product	
1.4 Product Category	Pls refer to the impacted (NXP) products list.	
1.5 Issue date	2026-07-09	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	David MONK, Simone FERRI
2.1.2 Marketing Manager	Marc OSAJDA
2.1.3 Quality Manager	Sixto ARJONILLA

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General (Logistic)	Delivery Note, Labels, Certificate of Conformity	ASECL, ATKL

4. Description of change

	Old	New
4.1 Description	PQ Box Label uses ASIC die as MAIN die	PQ Box Label uses MEMS die as MAIN die
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	Change in information of PQ Box Label
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Transition period; starting in August 2026 and finalized in March 2027
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7. Timing / schedule

7.1 Date of qualification results	2026-07-01
7.2 Intended start of delivery	2026-08-03
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

16483 Public product.pdf
16483 PCI_Change of Main Die Identification on Product Box PQ Label_GM.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	FXLS8964AFR3	
	FXLS8967AFR3	
	FXLS8971CFR1	
	FXPS7250DS4ST1	
	MPL3115A2ST1	
	NTM88K135ST1	
	FXLS8974CFR3	

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